What is claimed is:

- 1 1. An electronic apparatus comprising:
- 2 a function module having a multilayer wiring unit including
- 3 a first signal wiring corresponding to an internal layer wiring,
- 4 a first signal via, a first reference potential wiring, a first
- 5 signal pad to which the first signal wiring is connected through
- 6 the first signal via, a first reference potential pad that
- 7 surrounds the periphery of the first signal pad and to which
- 8 the first reference potential wiring is connected, and a first
- 9 reference potential via connected to the first reference
- 10 potential pad;
- 11 a multilayer circuit board including a second signal wiring
- 12 corresponding to an internal layer wiring, a second signal via,
- 13 a second reference potential wiring, a second signal pad to which
- 14 one end of the second signal wiring is connected through the
- 15 second signal via, a second reference potential pad that
- 16 surrounds the periphery of the second signal pad and to which
- one end of the second reference potential wiring is connected,
- 18 a second reference potential via connected to the second
- 19 reference potential pad, a third signal pad to which the other
- 20 end of the second signal wiring is connected, and a third reference
- 21 potential pad to which the other end of the second reference
- 22 potential wiring is connected;
- a first conductor that connects the first signal pad and
- 24 the second signal pad; and
- 25 a second conductor that connects the first reference
- 26 potential pad and the second reference potential pad,

- 27 wherein a central conductor of a coaxial cable is connected
- 28 to the third signal pad, and an outer conductor of the coaxial
- 29 cable is connected to the third reference potential pad.
 - 2. An electronic apparatus according to claim 1, wherein
 - 2 the first conductor is surrounded by a plurality of the second
 - 3 conductors.
 - 3. An electronic apparatus according to claim 1, wherein
- 2 in at least one of the multilayer wiring unit and the multilayer
- 3 circuit board, the signal via is surrounded by a plurality of
- 4 the reference potential vias.
- 1 4. An electronic apparatus according to claim 1, wherein
- 2 in at least one of the multilayer wiring unit and the multilayer
- 3 circuit board, the signal wiring is nipped by the two reference
- 4 potential wirings each wider than the signal wiring.
- 1 5. An electronic apparatus according to claim 1, wherein
- 2 the multilayer wiring unit includes a fourth pad connected to
- 3 the first reference potential pad, and the multilayer circuit
- 4 board includes a fifth pad connected to the second reference
- 5 potential pad and is provided with a third conductor that connects
- 6 the fourth pad and the fifth pad.
- 1 6. An electronic apparatus according to claim 1, wherein
- 2 one of the multilayer wiring unit and the multilayer circuit

- 3 board includes a fourth pad connected to the reference potential
- 4 pad, and the other thereof includes a fifth pad unconnected to
- 5 any ones and is provided with a third conductor that connects
- 6 the fourth pad and the fifth pad.
- 7. An electronic apparatus according to claim 1, wherein
- 2 the multilayer wiring unit includes a fourth pad unconnected
- 3 to any ones, and the multilayer circuit board includes a fifth
- 4 pad unconnected to any ones and is provided with a third conductor
- 5 that connects the fourth pad and the fifth pad.
- 1 8. An electronic apparatus according to claim 1, further
- 2 including a conductor case that is connected to the third
- 3 reference potential pad and the outer conductor of the coaxial
- 4 cable and thereby surrounds a connecting portion of the coaxial
- 5 cable.
- 9. An electronic apparatus according to claim 1, wherein
- 2 each conductor is any one of a bump, a ball and solder.
- 1 10. An electronic apparatus according to claim 1, wherein
- 2 the function module is a sensor module having the multilayer
- 3 wiring unit formed with a thin film.